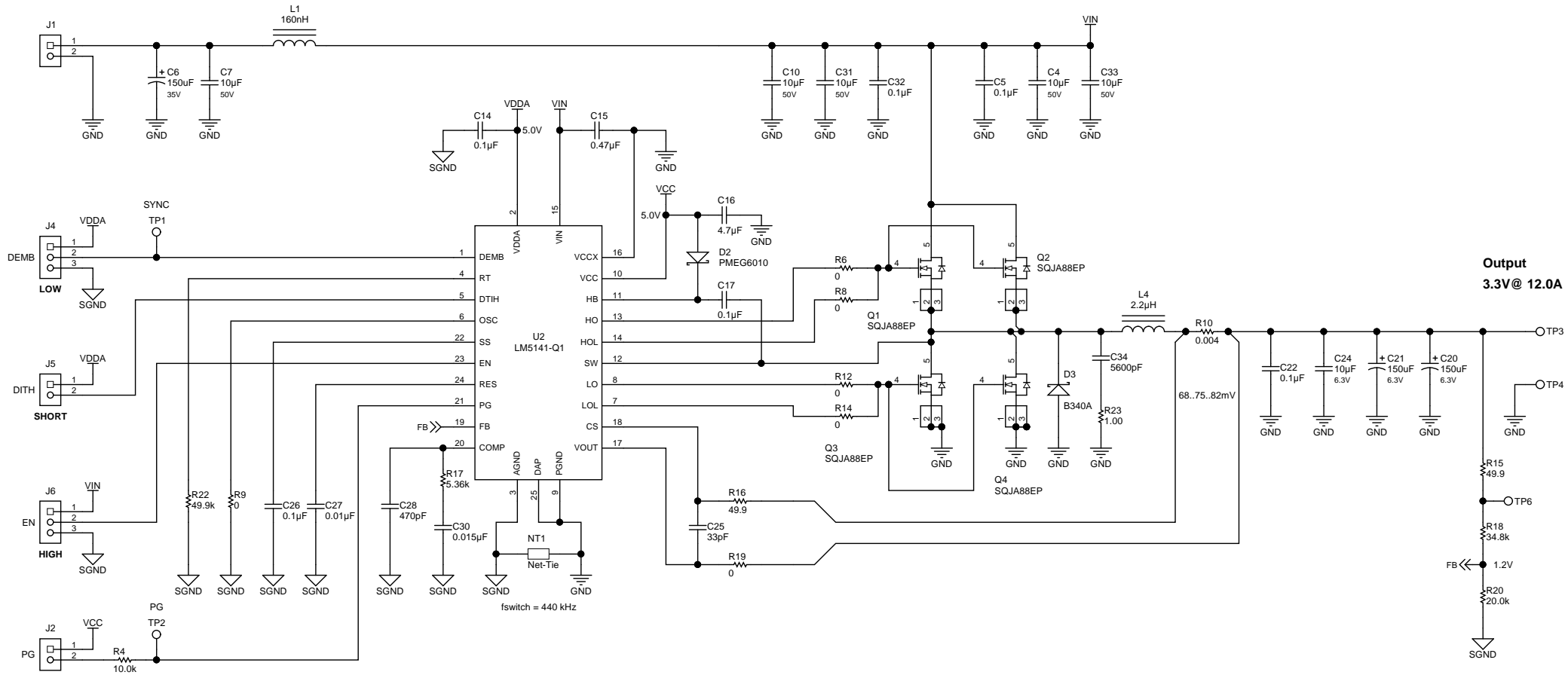


| Revision History |                  |
|------------------|------------------|
| Revision         | Notes            |
| A                | * Built & Tested |

**Input**  
**9.0 .. 18.0V continuous / 4.5 .. 32V short time operation**

**Worst Case Current Stress**  
 \* Input capacitor: 6.0A rms  
 \* High-side FET: 13.4A peak, 10.3A rms  
 \* Low-side FET: 13.4A peak, 10.9A rms  
 \* Inductor: 13.4A peak, 12.0A rms  
 \* Output capacitor: 0.8A rms



**Output**  
**3.3V @ 12.0A**

**J4 - DEMB - Diode Emulation Mode**  
 High: Forced PWM  
 Low: Diode Emulation Mode

**J5 - DITH - Dithering**  
 High: Dithering Off

**J6 - EN - Enable**  
 High: On  
 Low: Off

**Design Notes**  
 \* Built on PCB PMP20387 Rev.A  
 \* R15 for test purpose only

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|                                   |  |                      |
|-----------------------------------|--|----------------------|
| Orderable: EVM orderable          | Designed for: Public Release               | Mod. Date: 9/20/2017 |
| TID #: TID                        | Project Title: Automotive Synchronous Buck |                      |
| Number: PMP30339                  | Rev: A                                     | Sheet Title:         |
| SVN Rev: Version control disabled | Assembly Variant: [No Variations]          | Sheet: 1 of 1        |
| Drawn By:                         | File: PMP30339RevA_SchDoc                  | Size: A3             |
| Engineer: Matthias Ulmann         | Contact: http://www.ti.com/support         |                      |



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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